WHAT IS CLAIMED IS:

1. A integrated thermal dissipation device, comprising:

a thermal transfer device;

a standoff press disposed through a bore in base of the thermal transfer device;

a screw disposed through the bore in the base of the thermal device; and

a spring adapted to bias the screw against the thermal transfer device.

2. The integrated thermal dissipation device of claim 1, wherein the screw and spring bias through to the standoff press.

3. The integrated thermal dissipation device of claim 1, wherein the standoff press is press fit to the base of the thermal transfer device.

4. The integrated thermal dissipation device of claim 1, wherein the standoff press is threaded to the base of the thermal transfer device.

5. The integrated thermal dissipation device of claim 1, wherein the standoff press is fitted to the bore from the bottom of the thermal transfer device base.

6. The integrated thermal dissipation device of claim 5, wherein the screw is inserted to the bore from the top of the thermal transfer device base.

7. The integrated thermal dissipation device of claim 1 further comprising a counter-bore, wherein the counter-bore grasps the spring when the thermal transfer device is attached to a integrated circuit for reliable thermal performance.

8. The integrated thermal dissipation device of claim 2, wherein the spring is a tension spring and wherein the spring is disposed around the screw.

9. The integrated thermal device of claim 2, wherein the bottom threaded portion of the screw is adapted inside the standoff.

10. An electronic system, comprising:

a circuit board;

a integrated circuit disposed on the circuit board; and

a heat sink positioned in thermal contact with the integrated circuit; and

a integrated connection apparatus adapted to maintain the heat sink in contact with the integrated circuit, the integrated connection apparatus comprising:

a standoff press disposed through a bore in base of the heat sink;

a screw disposed through the bore in the base of the heat sink; and

a spring adapted to bias the screw against the heat sink.

11. The electronic system of claim 10, wherein the screw engages the integrated circuit when the bottom threaded portion of the screw engages the top of the heat sink base.

12. The electronic system of claim 11, wherein the standoff and spring are hidden in a counter-bore when the screw engages the integrated circuit.

13. The electronic system of claim 10, wherein the screw and spring bias through to the standoff press.

14. The electronic system of claim 10, wherein the standoff press is press fit to the base of heat sink.

15. The electronic system of claim 14, wherein the standoff press is fitted to the bore from the bottom of the heat sink base.

16. The electronic system of claim 14, wherein the screw is inserted to the bore from the top of the heat sink base.

17. The electronic system of claim 10 further comprising a counter-bore, wherein the counter-bore grasps the spring when the heat sink is attached to the integrated circuit for reliable thermal performance.

18. The electronic system of claim 10, wherein the bottom threaded portion of the screw is adapted inside the standoff.

19. An apparatus comprising:

a standoff press disposed through the bottom of a bore in a support base;

a screw disposed through the top of the bore in the support base; and

a spring adapted to bias the screw against a device to be retained,

wherein the screw and spring engage the standoff to attach the device to the support base.

20. The apparatus of claim 19 wherein the standoff is press fit to the support base.

21. The apparatus of claim 19 wherein the bottom threaded portion of the screw is adapted inside the standoff.